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**Amendments to the Claims:**

This listing of claims will replace all prior versions, and listings, of claims in the application:

**Listing of Claims:**

1. (Withdrawn- Currently Amended) A method to seal a film comprising a) using a resin in combination with an ethylene unsaturated ester copolymer in a sealing layer of a film or laminate to lower the sealing temperature of the sealing layer at least 3°C for a predetermined hot tack strength value when compared to the sealing temperature for the same ethylene unsaturated ester copolymer at the predetermined hot tack strength value, and b) heat sealing the film, wherein i) the ethylene-unsaturated ester copolymer is present at 75 to 99 wt% (based upon the weigh of the copolymer and the resin) and has a melt index of 35 g/10 min or less, ii) the resin is present at 1 to 25 wt% (based upon the weigh of the copolymer and the resin) and has a softening point of [[~~100~~]] 110 to 180 °C and the resin is selected from the group consisting of aliphatic hydrocarbon resins, hydrogenated aliphatic hydrocarbon resins, aliphatic/aromatic hydrocarbon resins, hydrogenated aliphatic/aromatic hydrocarbon resins, cycloaliphatic hydrocarbon resins, hydrogenated cycloaliphatic resins, cycloaliphatic/aromatic hydrocarbon resins, hydrogenated cycloaliphatic/aromatic hydrocarbon resins, aromatic hydrocarbon resins, hydrogenated aromatic hydrocarbon resins, grafted resins, and combinations thereof; iii) the combination of the resin and the ethylene unsaturated ester copolymer has a sealing temperature less than 115°C, and iv) the maximum hot tack of the sealing layer is greater than the maximum hot tack of the ethylene-unsaturated ester copolymer alone.

2. (Withdrawn- Previously Presented) The method of claim 1 to lower the sealing temperature of the sealing layer at least 5°C.

3. (Withdrawn- Previously Presented) The method of claim 1 to lower the sealing temperature of the sealing layer at least 10°C.

4. (Withdrawn- Currently Amended) A method to seal a film comprising a) using a resin in combination with an ethylene unsaturated ester copolymer in the sealing layer of a film or

laminate to extend the hot tack plateau at least 10°C above the maximum seal strength temperature (MSST) for the ethylene unsaturated copolymer alone while maintaining a hot tack strength greater than 50% of the value of the maximum hot tack strength value of the ethylene-unsaturated ester copolymer alone, and b) heat sealing the film, wherein i) the ethylene-unsaturated ester copolymer is present at 75 to 99 wt% (based upon the weigh of the copolymer and the resin) and has a melt index of 35 g/10 min or less, ii) the resin is present at 1 to 25 wt% (based upon the weigh of the copolymer and the resin) and has a softening point of [[~~100~~]] 110 to 180 °C and the resin is selected from the group consisting of aliphatic hydrocarbon resins, hydrogenated aliphatic hydrocarbon resins, aliphatic/aromatic hydrocarbon resins, hydrogenated aliphatic/aromatic hydrocarbon resins, cycloaliphatic hydrocarbon resins, hydrogenated cycloaliphatic resins, cycloaliphatic/aromatic hydrocarbon resins, hydrogenated cycloaliphatic/aromatic hydrocarbon resins, aromatic hydrocarbon resins, hydrogenated aromatic hydrocarbon resins, grafted resins, and combinations thereof; iii) the combination of the resin and the ethylene unsaturated ester copolymer has a sealing temperature less than 115°C, and iv) the maximum hot tack of the sealing layer is greater than the maximum hot tack of the ethylene-unsaturated ester copolymer alone.

5. (Withdrawn-Currently Amended) A method to seal a film comprising a) using a resin in combination with an ethylene unsaturated ester copolymer in the sealing layer of a film or laminate to extend the hot tack plateau at least 10°C above the MSST of the ethylene unsaturated copolymer alone while maintaining a hot tack strength greater than 70% of the value of the maximum hot tack strength value of the ethylene-unsaturated ester copolymer alone, and b) heat sealing the film, wherein i) the ethylene-unsaturated ester copolymer is present at 75 to 99 wt% (based upon the weigh of the copolymer and the resin) and has a melt index of 35 g/10 min or less, ii) the resin is present at 1 to 25 wt% (based upon the weigh of the copolymer and the resin) and has a softening point of [[~~100~~]] 110 to 180 °C and the resin is selected from the group consisting of aliphatic hydrocarbon resins, hydrogenated aliphatic hydrocarbon resins, aliphatic/aromatic hydrocarbon resins, hydrogenated aliphatic/aromatic hydrocarbon resins, cycloaliphatic hydrocarbon resins, hydrogenated cycloaliphatic resins, cycloaliphatic/aromatic hydrocarbon resins, hydrogenated cycloaliphatic/aromatic hydrocarbon resins, aromatic

hydrocarbon resins, hydrogenated aromatic hydrocarbon resins, grafted resins, and combinations thereof; iii) the combination of the resin and the ethylene unsaturated ester copolymer has a sealing temperature less than 115°C, and iv) the maximum hot tack of the sealing layer is greater than the maximum hot tack of the ethylene-unsaturated ester copolymer alone.

6. (Withdrawn- Previously Presented) The method of claim 1, 4, or 5 wherein the sealing layer comprises 80-95 wt% ethylene unsaturated ester copolymer and 5-20 wt% resin.

7. (Withdrawn- Previously Presented) The method of claim 1, 4, or 5 wherein the resin is selected from the group consisting of: hydrogenated aliphatic hydrocarbon resins, hydrogenated aliphatic/aromatic hydrocarbon resins, hydrogenated cycloaliphatic/aromatic hydrocarbon resins, hydrogenated aromatic hydrocarbon resins, -grafted resins, and mixtures of any two or more thereof.

8. (Withdrawn- Previously Presented) The method of claim 1, 4, or 5 wherein the ethylene-unsaturated ester copolymer is ethylene-vinyl acetate having greater than 10 wt% vinyl acetate.

9. (Withdrawn- Previously Presented) The method of claim 1, 4, or 5 wherein ethylene unsaturated ester copolymer is ethylene vinyl acetate having greater than 5 wt% vinyl acetate and the resin comprises a thermally polymerized hydrogenated aromatic-containing cyclopentadiene hydrocarbon resin.

10. (Currently Amended) A composition for use in the sealing layer of laminate or film to be applied to a substrate, the composition having a sealing temperature lower than 115°C, and consisting essentially of a combination of ethylene-unsaturated ester copolymer present at 75 to 99 wt% (based upon the weight of the copolymer and the resin) and having a melt index of 35 g/10 min or less and a resin present at 1 to 25 wt% (based upon the weight of the copolymer and the resin) wherein the resin has a softening point of [[~~100~~]] 110 to 180 °C and and the resin is selected from the group consisting of aliphatic hydrocarbon resins, hydrogenated aliphatic hydrocarbon resins, aliphatic/aromatic hydrocarbon resins, hydrogenated aliphatic/aromatic hydrocarbon resins, cycloaliphatic hydrocarbon resins, hydrogenated cycloaliphatic resins, cycloaliphatic/aromatic hydrocarbon resins, hydrogenated cycloaliphatic/aromatic hydrocarbon resins, aromatic hydrocarbon resins, hydrogenated aromatic hydrocarbon resins, grafted resins,

and combinations thereof; wherein during a heat sealing process the maximum hot tack of the sealing layer is greater than the maximum hot tack of the ethylene-unsaturated ester copolymer alone.

11. (Previously Presented) The composition according to claim 10 wherein at temperatures less than the maximum seal strength temperature (MSST) of the ethylene-unsaturated ester copolymer alone, the sealing temperature of the sealing layer is at least 3°C below the sealing temperature of the ethylene-unsaturated ester copolymer alone for a predetermined hot tack value.

12. (Previously Presented) The composition according to claim 10 or 11 wherein at temperatures greater than 10°C above the MSST of the ethylene-unsaturated ester copolymer alone, the hot tack strength of the sealing layer is greater than 50% of the value of the maximum hot tack strength of the ethylene-unsaturated ester copolymer alone.

13. (Original) The composition according to claim 10 wherein at temperatures less than the MSST of the ethylene-unsaturated ester copolymer alone, the sealing temperature of the sealing layer is at least 5°C below the sealing temperature of the ethylene-unsaturated ester copolymer alone for a predetermined hot tack value.

14. (Original) The composition according to claim 10 wherein at temperatures less than the MSST of the ethylene-unsaturated ester copolymer alone, the sealing temperature of the sealing layer is at least 10°C below the sealing temperature of the ethylene-unsaturated ester copolymer alone for a predetermined hot tack value.

15. (Previously Presented) The composition according to claim 10 consisting essentially of:

(a) 80 wt% or greater ethylene unsaturated ester copolymer and the ethylene unsaturated ester copolymer is an ethylene vinyl acetate copolymer having greater than 5 wt% vinyl acetate; and

(b) 20 wt% or less resin, wherein the resin is selected from the group consisting of: aliphatic/aromatic hydrocarbon resins, hydrogenated aliphatic/aromatic hydrocarbon resins, cycloaliphatic/aromatic hydrocarbon resins, hydrogenated cycloaliphatic/aromatic hydrocarbon resins, aromatic hydrocarbon resins, hydrogenated aromatic hydrocarbon resins, grafted resins, and mixtures of any two or more thereof.

16. (Withdrawn- Currently Amended) A process comprising:

(a) pre-determining a sealing temperature for a given hot tack for a film or laminate having a sealing layer consisting essentially of an ethylene unsaturated ester copolymer;

(b) providing a film or laminate having a sealing layer comprising from 1 to 25 wt % of a hydrocarbon resin and from 75 to 99 wt% of the ethylene unsaturated ester copolymer(based upon the weight of the copolymer and the resin); and,

(c) sealing the film or laminate at a temperature at least 3°C below the pre-determined sealing temperature, wherein i) the ethylene-unsaturated ester copolymer has a melt index of 35 g/10 min or less, ii) the resin has a softening point of [[~~100~~]] 110to 180 °C and the resin is selected from the group consisting of aliphatic hydrocarbon resins, hydrogenated aliphatic hydrocarbon resins, aliphatic/aromatic hydrocarbon resins, hydrogenated aliphatic/aromatic hydrocarbon resins, cycloaliphatic hydrocarbon resins, hydrogenated cycloaliphatic resins, cycloaliphatic/aromatic hydrocarbon resins, hydrogenated cycloaliphatic/aromatic hydrocarbon resins, aromatic hydrocarbon resins, hydrogenated aromatic hydrocarbon resins, grafted resins, and combinations thereof; iii) the combination of the resin and the ethylene unsaturated ester copolymer has a sealing temperature less than 115°C, and iv) the maximum hot tack of the sealing layer is greater than the maximum hot tack of the ethylene-unsaturated ester copolymer alone.

17. (Withdrawn) The process according to claim 16 comprising sealing the film or laminate at a temperature at least 5°C below the pre-determined sealing temperature.

18. (Withdrawn) The process according to claim 17 comprising sealing the film or laminate at a temperature at least 10°C below the pre-determined sealing temperature.

19. (Withdrawn) The process according to claim 16 wherein the sealing layer has been formed by mixing ethylene unsaturated ester copolymer with a masterbatch comprising 10-90 wt%

hydrocarbon resin and 90-10 wt% carrier polymer so that the hydrocarbon resin comprises less than 30 wt% of the total mixture.

20. (Withdrawn) The process according to claim 19 wherein the carrier polymer and ethylene unsaturated ester are ethylene vinyl acetate, and the ethylene vinyl acetate comprises greater than 70 wt% of the total mixture.

21. (Previously Presented) The composition according to claim 10 wherein the resin is a partially hydrogenated aromatic hydrocarbon resin having an aromatic content of 1 to 60%

22. (New) The composition according to claim 10 wherein the resin the resin has a softening point of 120 to 180 °C.

23. (New) The composition according to claim 10 wherein the resin the resin has a softening point of 130 to 180 °C.